

COMPLEMENTARY PAIR ENHANCEMENT MODE MOSFET

Product Summary

Device	V _{(BR)DSS}	R _{DS(ON)}	I _D T _A = 25°C
Q1	20V	$35m\Omega$ @ $V_{GS} = 4.5V$	4.5A
Qı	Q1 20V	56mΩ @ V _{GS} = 1.8V	3.5A
Q2 -20V		$74m\Omega$ @ $V_{GS} = -4.5V$	3.1A
Q2	-20V	168mΩ @ V _{GS} = -1.8V	2.0A

Description

This MOSFET has been designed to minimize the on-state resistance (R_{DS(on)}) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

Applications

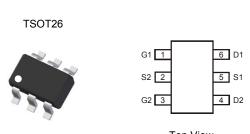
- Motor control
- Power Management Functions
- DC-DC Converters
- Backlighting

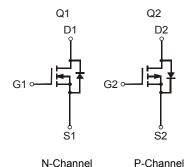
Features

- Low On-Resistance
- Low Input Capacitance
- Fast Switching Speed
- Low Input/Output Leakage
- Fast Switching Speed
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 standards for High Reliability

Mechanical Data

- Case: TSOT26
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals Matte Tin annealed over Copper leadframe.
 Solderable per MIL-STD-202, Method 208 (3)
- Terminal Connections Indicator: See diagram
- Weight: 0.013 grams (approximate)





Top View

Top View Pin Configuration

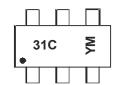
Ordering Information (Note 4)

Part Number	Qualification	Case	Packaging
DMC2038LVT-7	Commercial	TSOT26	3000/Tape & Reel
DMC2038LVTQ-7	Automotive	TSOT26	3000/Tape & Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html

Marking Information



31C = Product Type Marking Code YM = Date Code Marking Y = Year (ex: X = 2010) M = Month (ex: 9 = September)

Date Code Key

Year	201	0	2011		2012	20	13	2014		2015	2	2016
Code	X		Υ		Z	A	4	В		С		D
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D



Maximum Ratings N-CHANNEL – Q1 (@T_A = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Units	
Drain-Source Voltage		V _{DSS}	20	V	
Gate-Source Voltage			V _{GSS}	±12	V
		$T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$	I _D	3.7 3.0	А
Continuous Drain Current (Note 5) V _{GS} = 4.5V	t<10s	$T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$	I _D	4.1 3.2	Α
Continuous Drain Current (Note 6) 1/ 4 51/	Steady State	$T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$	I _D	4.5 3.6	Α
Continuous Drain Current (Note 6) V _{GS} = 4.5V	t<10s	$T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$	I _D	5.2 4.2	Α
Maximum Continuous Body Diode Forward Current	Is	1.5	Α		
Pulsed Drain Current (10μs pulse, duty cycle = 1%))		I _{DM}	25	Α

Maximum Ratings P-CHANNEL – Q2 (@T_A = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Units	
Drain-Source Voltage			V_{DSS}	-20	V
Gate-Source Voltage	_		V_{GSS}	±12	V
		T _A = +25°C T _A = +70°C	I _D	2.6 2.1	А
Continuous Drain Current (Note 5) V _{GS} = 4.5V	t<10s	T _A = +25°C T _A = +70°C	I _D	2.9 2.4	А
Continuous Prain Cornent (Note C) V	Steady State	T _A = +25°C T _A = +70°C	I _D	3.1 2.5	А
Continuous Drain Current (Note 6) V _{GS} = 4.5V	t<10s	T _A = +25°C T _A = +70°C	I _D	3.8 3.0	А
Maximum Continuous Body Diode Forward Current	Is	-1.5	Α		
Pulsed Drain Current (10μs pulse, duty cycle = 1%)			I _{DM}	-17	Α

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Units
Total Bower Dissipation (Note 5)	T _A = +25°C	Б	0.8	W
Total Power Dissipation (Note 5)	T _A = +70°C	P_{D}	0.5	VV
Thermal Resistance, Junction to Ambient (Note 5)	Steady State	- Г	168	°C/W
Thermal Resistance, Junction to Ambient (Note 5)	t<10s	$R_{\theta JA}$	120	C/VV
Total Power Dissipation (Note 6)	$T_A = +25^{\circ}C$	Б	1.1	W
Total Fower Dissipation (Note 6)	T _A = +70°C	P_{D}	0.7	VV
Thermal Desistance, Junction to Ambient (Note 6)	Steady State	П	114	
Thermal Resistance, Junction to Ambient (Note 6)	t<10s	$R_{\theta JA}$	72	°C/W
Thermal Resistance, Junction to Case (Note 6)		$R_{ heta JC}$	39	
Operating and Storage Temperature Range		$T_{J_1}T_{STG}$	-55 to +150	°C

Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.
 Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate.

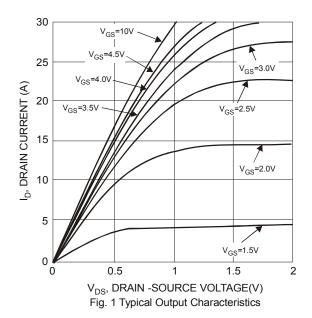


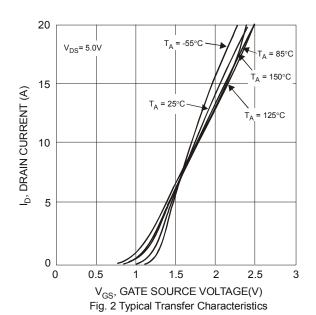
Electrical Characteristics N-CHANNEL - Q1 (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 7)							
Drain-Source Breakdown Voltage	BV _{DSS}	20	1	-	V	$V_{GS} = 0V, I_D = 250\mu A$	
Zero Gate Voltage Drain Current @T _c = +25°C	I _{DSS}	-	-	1.0	μΑ	V_{DS} =16V, V_{GS} = 0V	
Gate-Source Leakage	I _{GSS}	-	-	±100	nA	$V_{GS} = \pm 12V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 7							
Gate Threshold Voltage	V _{GS(th)}	0.4	-	1.0	V	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	
		-	27	35		$V_{GS} = 4.5V$, $I_D = 4.0A$	
Static Drain-Source On-Resistance	R _{DS} (ON)	-	33	43	mΩ	$V_{GS} = 2.5V$, $I_D = 2.5A$	
	== (=)	-	43	56		V _{GS} = 1.8V, I _D = 1.5A	
Forward Transfer Admittance	Y _{fs}	-	9	-	S	$V_{DS} = 5V, I_{D} = 3.4A$	
Diode Forward Voltage	V_{SD}	0.4	-	1.1	V	$V_{GS} = 0V, I_{S} = 1A$	
DYNAMIC CHARACTERISTICS (Note 8)							
Input Capacitance	C _{iss}	-	400	530	pF	10/11/	
Output Capacitance	Coss	-	70	90	pF	V _{DS} = 10V, V _{GS} = 0V, -f = 1.0MHz	
Reverse Transfer Capacitance	C _{rss}	-	65	100	pF	1 - 1.0WI IZ	
Gate Resistance	R_g	-	1.9	-	Ω	$V_{DS} = 0V$, $V_{GS} = 0V$, $f = 1MHz$	
Total Gate Charge (V _{GS} = 4.5V)	Q_g	-	5.7	-	nC		
Total Gate Charge (V _{GS} = 10V)	Qg	-	12	17	nC	\/ - 15\/ \ - 5 0 0	
Gate-Source Charge	Q _{gs}	-	0.7	-	nC	$V_{DS} = 15V, I_D = 5.8A$	
Gate-Drain Charge	Q _{gd}	-	1.4	-	nC		
Turn-On Delay Time	t _{D(on)}	-	5	10	ns		
Turn-On Rise Time	t _r	-	8	16	ns	$V_{DS} = 10V, V_{GS} = 4.5V,$	
Turn-Off Delay Time	t _{D(off)}	-	25	40	ns	$R_G = 6\Omega$, $I_{DS} = 1A$,	
Turn-Off Fall Time	t _f	-	8	16	ns		

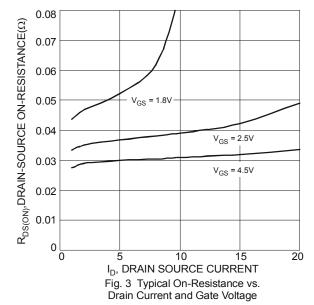
Notes:

- 7. Short duration pulse test used to minimize self-heating effect. 8. Guaranteed by design. Not subject to product testing.









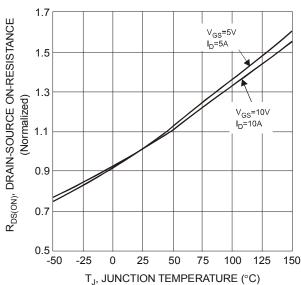


Fig. 5 On-Resistance Variation with Temperature

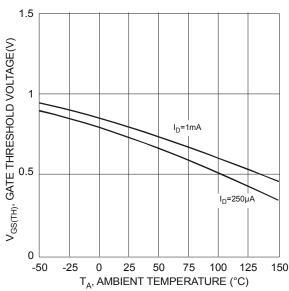
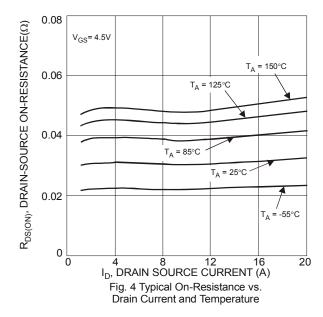
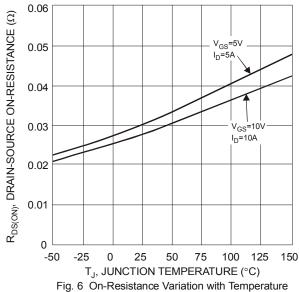


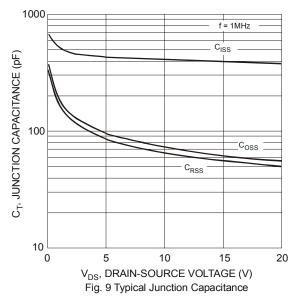
Fig. 7 Gate Threshold Variation vs. Ambient Temperature

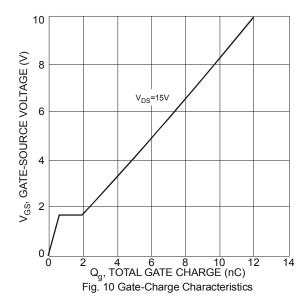


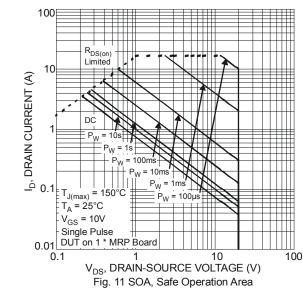


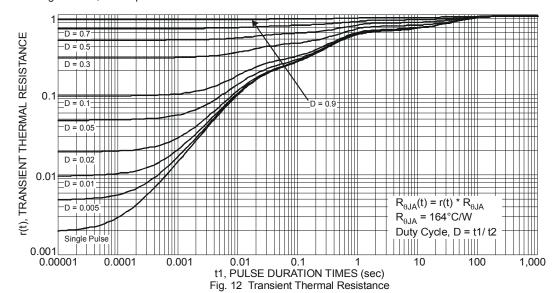
20 18 16 Is, SOURCE CURRENT (A) T_A= 25°C 12 10 8 6 2 0 0.6 0.2 0.4 8.0 1 1.2 1.4 V_{SD}, SOURCE-DRAIN VOLTAGE (V) Fig. 8 Diode Forward Voltage vs. Current









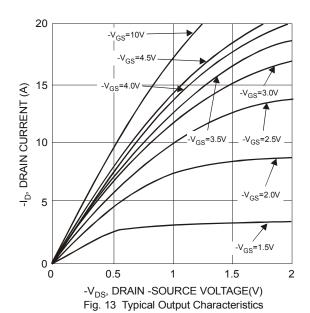


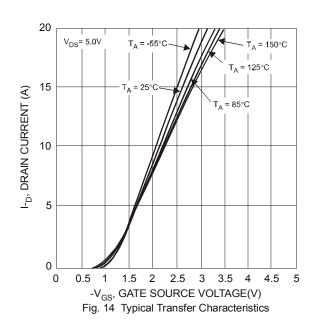


Electrical Characteristics P-CHANNEL – Q2 (@T_A = +25°C, unless otherwise specified.)

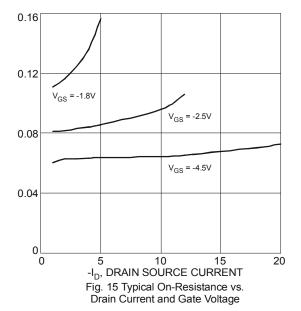
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 7)							
Drain-Source Breakdown Voltage	BV_{DSS}	-20	1	-	٧	$V_{GS} = 0V$, $I_D = -250\mu A$	
Zero Gate Voltage Drain Current @T _c = +25°C	I _{DSS}	-	1	-1.0	μΑ	$V_{DS} = -16V, V_{GS} = 0V$	
Gate-Source Leakage	I _{GSS}	-	-	±100	nA	$V_{GS} = \pm 12V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 7)							
Gate Threshold Voltage	$V_{GS(th)}$	-0.4	-	-1.0	V	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	
		-	57	74		$V_{GS} = -4.5V$, $I_D = -3.0A$	
Static Drain-Source On-Resistance	R _{DS} (ON)	-	76	110	mΩ	$V_{GS} = -2.5V$, $I_D = -1.5A$	
	, ,	-	102	168		$V_{GS} = -1.8V$, $I_{D} = -1.0A$	
Forward Transfer Admittance	Y _{fs}	-	10	-	S	$V_{DS} = -5V, I_{D} = -3.0A$	
Diode Forward Voltage	V_{SD}	-	-0.8	-1.0	V	$V_{GS} = 0V, I_{S} = -0.6A$	
DYNAMIC CHARACTERISTICS (Note 8)							
Input Capacitance	Ciss	-	530	705	рF	101/1/	
Output Capacitance	Coss	-	70	95	pF	$V_{DS} = -10V, V_{GS} = 0V,$ - f = 1.0MHz	
Reverse Transfer Capacitance	C _{rss}	-	60	90	pF	1 - 1.0WH12	
Gate Resistance	R_g	-	72	-	Ω	V_{DS} = 0V, V_{GS} = 0V, f = 1MHz	
Total Gate Charge (V _{GS} = -4.5V)	Q_g	-	7	10	nC		
Total Gate Charge (V _{GS} = -10V)	Qg	-	14	-	nC	\\ - 45\\\ - CA	
Gate-Source Charge	Q_{gs}	-	0.95	-	nC	V _{DS} = -15V,I _D = -6A	
Gate-Drain Charge	Q_{qd}	-	1.2	-	nC		
Turn-On Delay Time	t _{D(on)}	-	11	20	nS		
Turn-On Rise Time	t _r	-	12	22	nS	$V_{DS} = -10V, V_{GS} = -4.5V,$	
Turn-Off Delay Time	t _{D(off)}	-	21	34	nS	$R_G = 6\Omega$, $I_S = -1A$,	
Turn-Off Fall Time	t _f	-	13	23	nS		

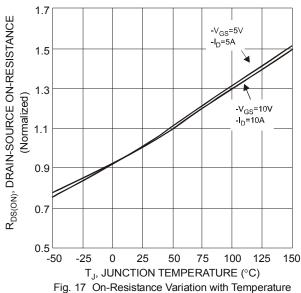
7. Short duration pulse test used to minimize self-heating effec 8. Guaranteed by design. Not subject to product testing.











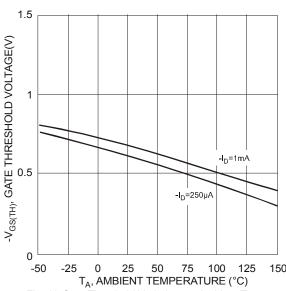
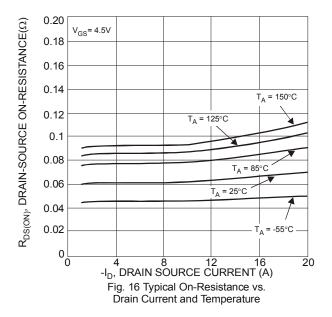


Fig. 19 Gate Threshold Variation vs. Ambient Temperature



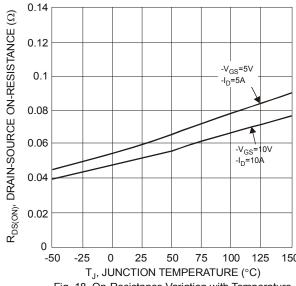


Fig. 18 On-Resistance Variation with Temperature

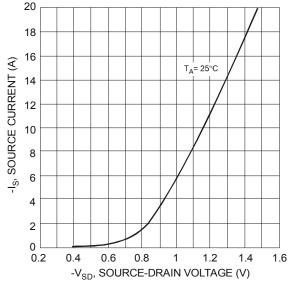
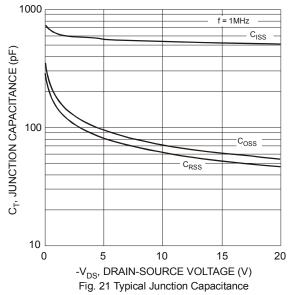
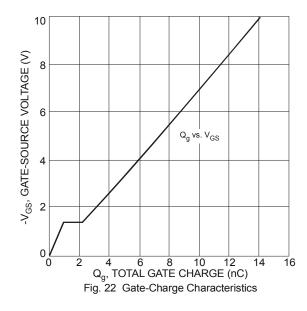
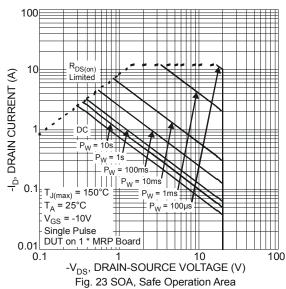


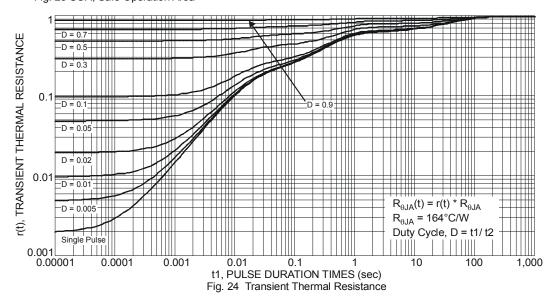
Fig. 20 Diode Forward Voltage vs. Current







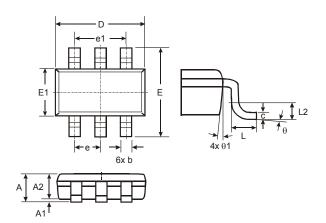






Package Outline Dimensions

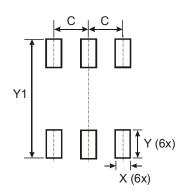
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.



TSOT26							
Dim	Min	Max	Тур				
Α	_	1.00	-				
A1	0.01	0.10	_				
A2	0.84	0.90	_				
D	2.85	2.95	2.90				
Е	2.70	2.90	2.80				
E1	1.55	1.65	1.60				
b	0.30	0.45	-				
С	0.12	0.20	_				
е	BSC	BSC	0.95				
e1	BSC	BSC	1.90				
L	0.30	0.50					
L2	BSC	BSC	0.25				
θ	0°	8°	4°				
θ1	4°	12°	-				
All D	imens	ions ir	n mm				

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
С	0.950
X	0.700
Y	1.000
Y1	3 199



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